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(54) **COMPACT FOLDED CONFIGURATION FOR INTEGRATED CIRCUIT PACKAGING**

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USPC **361/789**; 361/749; 361/803; 361/816; 174/254; 174/258

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USPC 174/254–260; 361/749, 803, 782–784, 361/816, 818
See application file for complete search history.

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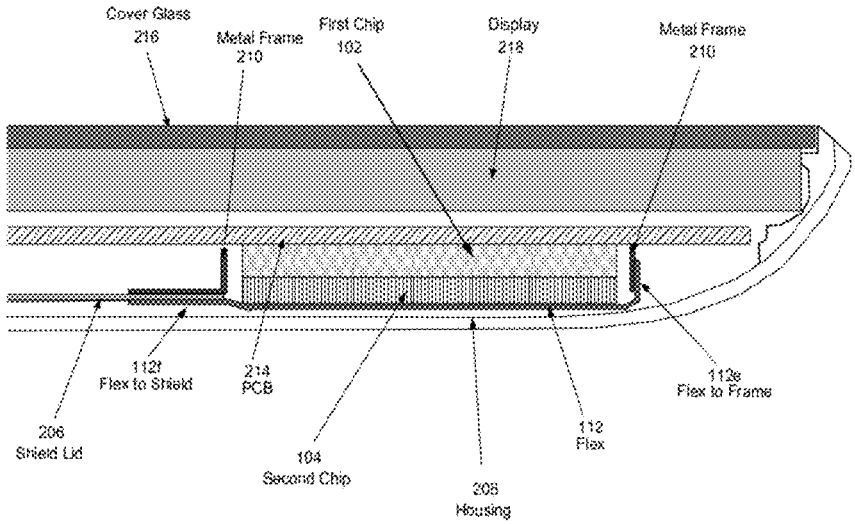
(57) **ABSTRACT**

A memory unit for a computing device is described. The memory device can include a number of memory chips, such as flash nand chips, linked together via a flexible circuit connector. During installation of the memory device, portions of the flexible circuit connector can be bent or folded in different locations to allow an orientation of the memory chips to be changed relative to one another. In one embodiment, a memory device with a number of chips can be provided in a flat configuration and then can be folded to allow the chips to be installed in a stacked configuration. In another embodiment, the flexible circuit connector can be grounded to other conductive components to allow the flexible circuit connector to be used as part of a faraday cage surrounding the memory chips.

14 Claims, 9 Drawing Sheets